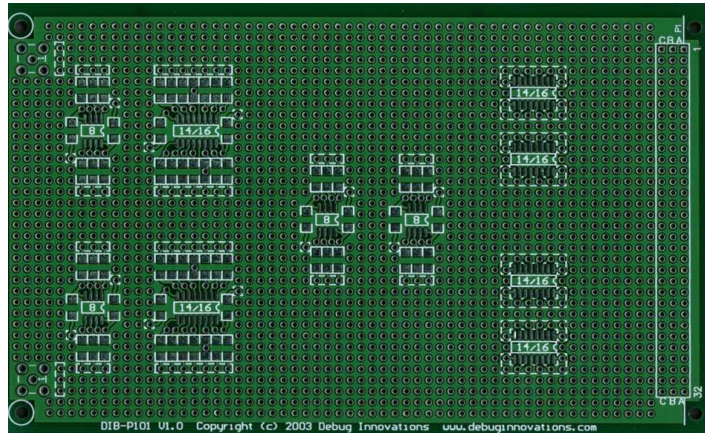


DIB-P101

High Speed Surface Mount Prototyping Board

This unique design allows prototyping of circuits incorporating both surface mount and through hole components. Special patches incorporating pre-wired discrete component positions simplify the design of analogue and high speed digital circuits avoiding the need for special sockets and reducing the amount of wiring required. Accessible power planes and pre-tracked decoupling capacitor patches give excellent electrical performance making this board suitable for precision analogue and RF prototyping.



Ideal for

- High speed logic prototyping
- Mixed analogue / digital device prototyping
- Mixed RF / digital prototyping
- Surface mount device evaluation

Large 0.1" matrix with power/ground planes for

- DIL devices
- Connectors
- Discretes
- Adaptor sockets for non-SOIC footprint devices e.g. FPGAs

Careful layout of matrix allows space for

- SMD to SMD or SMD to through hole connections
- 0.1" pitch edge connectors
- Connectors for stacking or sideways expansion
- 2 x SMA/SMB/SMC connector patches for RF connections
- Buffer or termination components near to the connectors

Single Eurocard format with 96-way DIN41612 connector patch

- Industry standard size for compatibility with a wide range of racks and PCB products
- Standard Eurocard mounting holes and 96 way connector
- High quality fibre glass laminate PCB construction
- Hot air levelled tin plated pads throughout for ease of soldering
- Legend on all patches shows pre-wired pins
- Solder mask on all component positions reduces the risk of shorts

Unique multi-patch architecture

- 4 x SOIC-14/16 minimal footprint patches designed primarily for use with digital logic and similar devices. All pins are tracked to holes on the 0.1" matrix. Each patch has a pre-wired decoupling capacitor space on the reverse side of the board across pins 16 to 8 and 14 to 7.
- 2 x SOIC-14/16 patches with pre-wired spaces for discrete devices on every pin designed for analogue and special function ICs requiring support resistors, capacitors etc. All pins are tracked to holes that can be directly wired or used as test points then connected through a 1206 patch to holes on the 0.1" matrix. Each patch has a pre-wired decoupling capacitor space on the reverse side of the board across pins 16 to 8 and 14 to 7.
- 4 x SOIC-8 patches with pre-wired spaces for discrete devices on every pin designed for op-amps and other small ICs requiring support resistors, capacitors etc. All pins are tracked to holes that can be directly wired or used as test points then connected through a 1206 patch to holes on the 0.1" matrix. Each patch has a pre-wired decoupling capacitor space on the reverse side of the board across pins 8 to 4 and 7 to 4 and a pre-wired feedback resistor/capacitor space across pins 6 to 2 for use with standard pinout op-amps.
- Total pinout flexibility – all device pins are open circuit unless the discrete patches are used
- Discrete patches use 1206 footprint for manageable hand soldering and wide component choice

For more information visit www.debuginnovations.com or email info@debuginnovations.com